

**N-Ch MOSFET** 

## **General Description**

The WSC40N06 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSC40N06 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

**Absolute Maximum Ratings** 

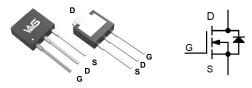
# **Product Summery**

| BVDSS | RDSON | ID  |
|-------|-------|-----|
| 60V   | 20mΩ  | 50A |

#### Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- LCD/LED back light

#### **TO-251 Pin Configuration**



| Symbol                               | Parameter  | Rating | Units |
|--------------------------------------|--|--------|-------|
| V <sub>DS</sub>                      | Drain-Source Voltage   | 60     | V     |
| V <sub>GS</sub>                      | Gate-Source Voltage  | ±20    | V     |
| I <sub>D</sub> @T <sub>C</sub> =25℃  | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | 50     | A     |
| I <sub>D</sub> @T <sub>C</sub> =100℃ | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | 32     | А     |
| I <sub>D</sub> @T <sub>A</sub> =25℃  | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | 10     | А     |
| I <sub>D</sub> @T <sub>A</sub> =70℃  | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | 8      | А     |
| I <sub>DM</sub>                      | Pulsed Drain Current <sup>2</sup>                            | 200    | А     |
| EAS                                  | Single Pulse Avalanche Energy <sup>3</sup>                   | 42     | mJ    |
| I <sub>AS</sub>                      | Avalanche Current  | 28     | A     |
| P₀@T₀=25℃                            | Total Power Dissipation <sup>4</sup>                         | 53     | W     |
| P <sub>D</sub> @T <sub>A</sub> =25℃  | Total Power Dissipation <sup>4</sup>                         | 3.5    | W     |
| T <sub>STG</sub>                     | Storage Temperature Range -55 to 150                         |        | °C    |
| TJ                                   | Operating Junction Temperature Range -55 to 150              |        | °C    |

#### **Thermal Data**

| Symbol           | Parameter  | Тур. | Max. | Unit |
|------------------|--|------|------|------|
| R <sub>θJA</sub> | Thermal Resistance Junction-Ambient <sup>1</sup> |      | 62   | °C/W |
| R <sub>eJC</sub> | Thermal Resistance Junction-Case <sup>1</sup>    |      | 2    | °C/W |



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#### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

| Symbol                               | Parameter                                      | Conditions   | Min. | Тур.  | Max. | Unit      |
|--------------------------------------|--|--|------|-------|------|-----------|
| BV <sub>DSS</sub>                    | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V , I <sub>D</sub> =250uA                        | 60   |       |      | V         |
| $\triangle BV_{DSS} / \triangle T_J$ | BV <sub>DSS</sub> Temperature Coefficient      | Reference to 25 $^\circ\!\mathrm{C}$ , I_D=1mA                     |      | 0.057 |      | V/℃       |
| Б                                    | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =10V , I <sub>D</sub> =20A                         |      | 20    | 23   | mΩ        |
| R <sub>DS(ON)</sub>                  | Static Drain-Source On-Resistance              | V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A                        |      | 23    | 28   |           |
| V <sub>GS(th)</sub>                  | Gate Threshold Voltage                         |  | 1.2  | 1.8   | 2.5  | V         |
| $	riangle V_{GS(th)}$                | V <sub>GS(th)</sub> Temperature Coefficient    | $V_{GS}=V_{DS}$ , $I_{D}=250$ uA                                   |      | -5.68 |      | mV/℃      |
|                                      | Drain Source Lookage Current                   | V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃   |      |       | 1    |           |
| I <sub>DSS</sub>                     | Drain-Source Leakage Current                   | V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃   |      |       | 5    | uA        |
| I <sub>GSS</sub>                     | Gate-Source Leakage Current                    | $V_{GS}=\pm20V$ , $V_{DS}=0V$                                      |      |       | ±100 | nA        |
| gfs                                  | Forward Transconductance                       | V <sub>DS</sub> =5V , I <sub>D</sub> =15A                          |      | 33    |      | S         |
| Rg                                   | Gate Resistance                                | V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz                 |      | 1.7   | 3.4  | Ω         |
| Qg                                   | Total Gate Charge (4.5V)                       |  |      | 28    | 36   |           |
| Q <sub>gs</sub>                      | Gate-Source Charge                             | V <sub>DS</sub> =30V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A |      | 3.5   | 10   | nC        |
| Q <sub>gd</sub>                      | Gate-Drain Charge                              |  |      | 6.5   | 15   |           |
| T <sub>d(on)</sub>                   | Turn-On Delay Time                             |  |      | 7.2   | 14.4 |           |
| Tr                                   | Rise Time                                      | $V_{DD}$ =30V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$ ,            |      | 38    | 90   |           |
| T <sub>d(off)</sub>                  | Turn-Off Delay Time                            | I <sub>D</sub> =15A  |      | 34    | 73   | - ns<br>- |
| T <sub>f</sub>                       | Fall Time                                      |  |      | 8.2   | 15.2 |           |
| Ciss                                 | Input Capacitance                              | V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz                |      | 1680  | 2578 |           |
| C <sub>oss</sub>                     | Output Capacitance                             |  |      | 115   | 203  | pF        |
| C <sub>rss</sub>                     | Reverse Transfer Capacitance                   |  |      | 85    | 136  | 1         |

## **Guaranteed Avalanche Characteristics**

| Symbol | Parameter                      | Conditions  | Min. | Тур. | Max. | Unit |
|--------|--------------------------------|---|------|------|------|------|
| EAS    | Single Pulse Avalanche Energy⁵ | V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =15A | 19   |      |      | mJ   |

#### **Diode Characteristics**

| Symbol          | Parameter                                | Conditions   | Min. | Тур. | Max. | Unit |
|-----------------|--|--|------|------|------|------|
| ls              | Continuous Source Current <sup>1,6</sup> | $V_G = V_D = 0V$ , Force Current                   |      |      | 50   | A    |
| I <sub>SM</sub> | Pulsed Source Current <sup>2,6</sup>     |  |      |      | 200  | A    |
| V <sub>SD</sub> | Diode Forward Voltage <sup>2</sup>       | V <sub>GS</sub> =0V , I <sub>S</sub> =20A , TJ=25℃ |      |      | 1.2  | V    |
| t <sub>rr</sub> | Reverse Recovery Time                    | IF=1A ,dl/dt=100A/µs,TJ=25℃                        |      | 19.6 |      | nS   |
| Q <sub>rr</sub> | Reverse Recovery Charge                  |  |      | 14.2 |      | nC   |

Note :

1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width  $\,\leq\,$  300us , duty cycle  $\,\leq\,$  2%

3. The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}\text{=}25\text{V}, V_{\text{GS}}\text{=}10\text{V}, \text{L=}0.1\text{mH}, \text{I}_{\text{AS}}\text{=}15\text{A}$ 

4.The power dissipation is limited by 150  $^\circ\!\!\mathbb{C}$  junction temperature

5. The Min. value is 100% EAS tested guarantee.

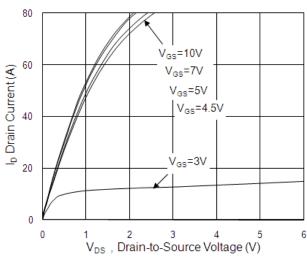
6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



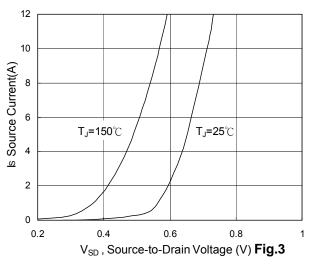
# WSC40N06

**N-Ch MOSFET** 

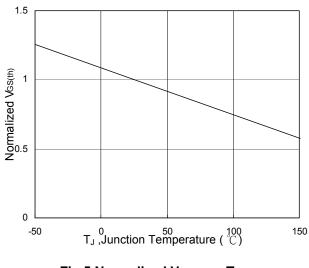




**Fig.1 Typical Output Characteristics** 



Forward Characteristics of Reverse





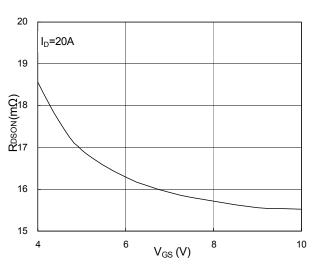


Fig.2 On-Resistance v.s Gate-Source

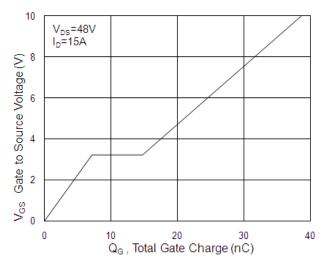
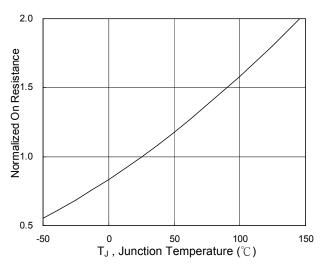
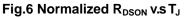
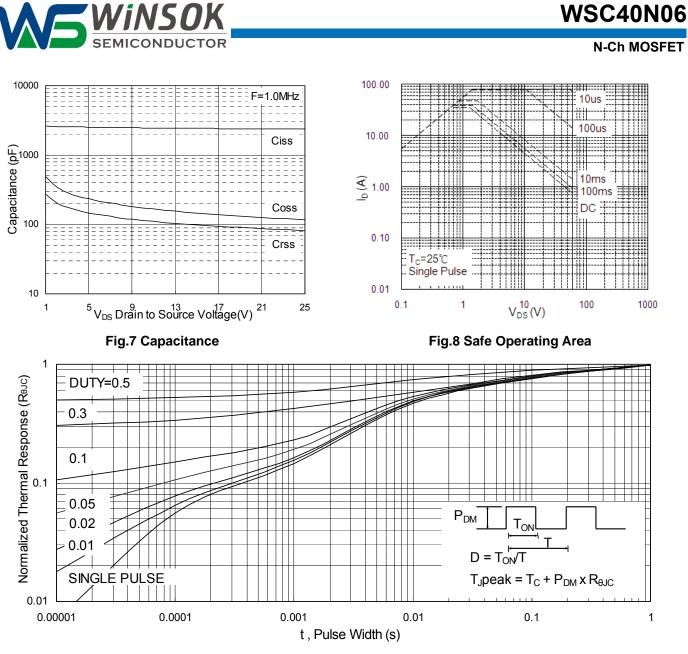


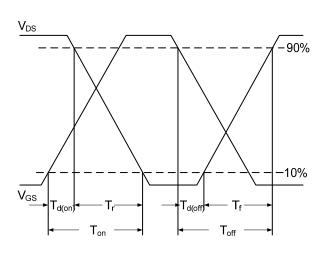
Fig.4 Gate-Charge Characteristics













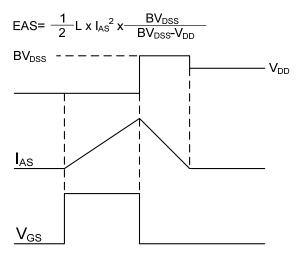


Fig.11 Unclamped Inductive Switching Waveform



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